

isola

IS420

High Performance Laminate and Prepreg

IS420 is a high performance 170°C glass transition temperature (Tg) FR-4 system for multilayer Printed Wiring Board (PWB) applications where maximum thermal performance and reliability are required.

IS420 laminate and prepreg products are manufactured with a unique high performance multifunctional epoxy resin, reinforced with electrical grade (E-glass) glass fabric. This system provides improved thermal performance and low expansion rates in comparison to traditional FR-4 while retaining FR-4 processability. In addition to this superior thermal performance, the mechanical, chemical and moisture resistance properties all equal or exceed the performance of traditional FR-4 materials. The IS420 system is also laser fluorescing and UV blocking for maximum compatibility with Automated Optical Inspection (AOI) systems, optical positioning systems and photoimagable solder mask imaging.

Product Attributes

Legacy Materials , High Thermal Reliability

ORDERING INFORMATION:

Contact your local sales representative or visit www.isola-group.com for further information.

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Data Sheet

Tg 170°C Td 350°C Dk 4.04 Df 0.021

IPC-4101 - / 98 / 99 / 101 UL - File Number E41625

> Last Updated May 7, 2019 Revision No: C

Product Features

- · Industry Recognition
 - UL File Number: E41625
 - Qualified to UL's MCIL Program
 - RoHS Compliant
- · Performance Attributes
 - Lead-free assembly compatible
- · Processing Advantages
 - FR-4 process compatible
 - UV blocking and AOI fluorescence

Product Availability

- · Standard Material Offering: Laminate
 - 2 to 93 mil (0.05 to 2.4 mm)
 - Available in full size sheet or panel form
- · Copper Foil Type
 - HTE Grade 3
 - RTF (Reverse Treat Foil)
- · Copper Weight
 - $\frac{1}{2}$ to 2 oz (18 to 70 µm) available
 - Heavier copper available
 - Thinner copper foil available
- Standard Material Offering: Prepreg
 - Roll or panel form
 - Tooling of prepreg panels
- · Glass Fabric Availability
 - E-glass
 - Square weave glass

| Property | | Typical Value | Units | Test Method |
|--------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------------------------|-----------------------|--------------------------------------------------------------------------------------|
| | | | Metric (English) | IPC-TM-650 (or as noted) |
| Glass Transition Temperature (Tg) by DSC | | 170 | °C | 2.4.25C |
| Decomposition Temperature (Td) by TGA @ 5% weight loss | | 350 | °C | 2.4.24.6 |
| Time to Delaminate by TMA (Copper removed) | A. T260 B. T288 | 60 >15 | Minutes | 2.4.24.1 |
| Z-Axis CTE | A. Pre-Tg B. Post-Tg C. 50 to 260°C, (Total Expansion) | 45 230 2.8 | ppm/°C ppm/°C % | 2.4.24C |
| X/Y-Axis CTE | Pre-Tg | 13/14 | ppm/°C | 2.4.24C |
| Thermal Conductivity | | 0.4 | W/mK | ASTM E1952 |
| Thermal Stress 10 sec @ 288ºC (550.4ºF) | A. Unetched B. Etched | Pass | Pass Visual | 2.4.13.1 |
| Dk, Permittivity | A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz | 4.24 4.17 4.04 3.92 3.92 | I | 2.5.5.3 2.5.5.9 Bereskin Stripline Bereskin Stripline Bereskin Stripline |
| Df, Loss Tangent | A. @ 100 MHz B. @ 1 GHz C. @ 2 GHz D. @ 5 GHz E. @ 10 GHz | 0.0150 0.0161 0.0210 0.0250 0.0250 | ı | 2.5.5.3 2.5.5.9 Bereskin Stripline Bereskin Stripline Bereskin Stripline |
| Volume Resistivity | A. After moisture resistance B. At elevated temperature | 3.0 x 10 ⁸ 7.0 x 10 ⁸ | MΩ-cm | 2.5.17.1 |
| Surface Resistivity | A. C-96/35/90 B. After moisture resistance C. At elevated temperature | - 3.0 x 10 ⁶ 2.0 x 10 ⁸ | МΩ | 2.5.17.1 |
| Dielectric Breakdown | | >50 | kV | 2.5.6B |
| Arc Resistance | | 115 | Seconds | 2.5.1B |
| Electric Strength (Laminate & laminated prepreg) | | 54 (1350) | kV/mm (V/mil) | 2.5.6.2A |
| Comparative Tracking Index (CTI) | | 3 (175-249) | Class (Volts) | UL 746A ASTM D3638 |
| Peel Strength | A. Low profile copper foil and very low profile copper foil all copper foil >17 μm [0.669 mil] B. Standard profile copper 1. After thermal stress 2. At 125°C (257°F) 3. After process solutions | 1.14 (6.5) 1.25 (7.0) 1.25 (7.0) 1.14 (6.5) | N/mm (lb/inch) | 2.4.8C 2.4.8.2A 2.4.8.3 2.4.8.3 |
| Flexural Strength | A. Length direction B. Cross direction | 82.7 60.9 | ksi | 2.4.4B |
| Moisture Absorption | | 0.15 | % | 2.6.2.1A |
| Flammability (Laminate & laminated prepreg) | | V-0 | Rating | UL 94 |
| Relative Thermal Index (RTI) | | 130 | °C | UL 796 |

The data, while believed to be accurate and based on analytical methods considered to be reliable, is for information purposes only. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.



NOTE

Visit our site http://www.isola-group.com for more details. Revisions:

A: Initial release - 4/17

B: Corrected units for Flexural Strength - 8/18

C: Change MOT to RTI 5/19